



Semiconductor Device Type: C3X-SOIJ-8-.208in-MatteTin

Material	Substance	CAS Number	Mass of Substance in Material (mg)	Mass of Material (mg)	Percentage of Substance in Material	Percentage of Material in Product	Percentage of Substance in Product	Amount of Substance in Product (ppm)
Die				9.33	100.00%	7.50%		
	Silicon	7440-21-3	9.33		100.00%		7.50%	75000
Plating & Anode Ball				1.56	100.00%	1.25%		
	Other	Trade Secret	0.00		0.10%		0.00%	13
	Tin	7440-31-5	1.56		99.90%		1.25%	12528
Lead Frame				12.93	100.00%	10.39%		
	Zinc	7440-66-6	0.03		0.20%		0.02%	210
	Iron	7439-89-6	0.34		2.63%		0.27%	2730
	Lead	7439-92-1	0.00		0.00%		0.00%	4
	Copper	7440-50-8	12.54		97.02%		10.08%	100833
	Phosphorus	7723-14-0	0.02		0.15%		0.02%	157
Lead Frame Plating				0.13	100.00%	0.10%		
	Silver	7440-22-4	0.13		100.00%		0.10%	1050
Die Attach				0.93	100.00%	0.75%		
	Formaldehyde, Polymer with 2-(chloromethyl)oxirane and Phenol	9003-36-5	0.09		10.00%		0.07%	748
	2,2'-[[2-(2-Oxiranylmethoxy)-1,3-phenylene]bis(methylene)]bis[oxirane]	13561-08-5	0.09		10.00%		0.07%	748
	Silver	7440-22-4	0.65		70.00%		0.52%	5233
	Fatty Acids, C18-unsatd., Dimers, Polymers with Epichlorohydrin	68475-94-5	0.09		10.00%		0.07%	748
Mold Compound				99.27	100.00%	79.80%		
	Silica (Fused)	60676-86-0	79.91		80.50%		64.24%	642382
	o-Cresol-epichlorohydrin-formaldehyde Copolymer	29690-82-2	2.98		3.00%		2.39%	23940
	Epoxy Resin	Trade Secret	7.94		8.00%		6.38%	63839
	Carbon Black	1333-86-4	0.50		0.50%		0.40%	3990
	Phenolic Resin	Trade Secret	7.94		8.00%		6.38%	63839
Bond Wire				0.25	100.00%	0.20%		
	Gold	7440-57-5	0.25		100.00%		0.20%	2009
Totals			124.40	124.40		100.00%	100.00%	1000000

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